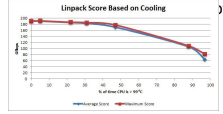


## Problem Definition

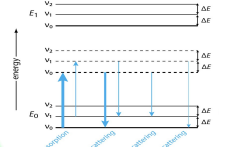
Modern electronic devices such as CPU's and micro electronics are limited by thermal management challenges that reduce performance, efficiency and lifetime. Conventional cooling methods like air and liquid cooling introduce mechanical vibrations and scaling limitations at small length scales.

Anti-Stokes laser cooling provides a solid state alternative that can overcome the bottleneck of heat conduction on conventional cooling.



Lump sum used to determine its performance, decreases sharply in hotspot areas above 99°C. By decreasing the heat at the hotspot, the chip can maintain higher speeds and increase overall performance.

### Anti-Stokes Mechanism



When an emitted photon has a higher energy than the absorbed one, the energy difference comes from lattice vibrations (phonons), which produces a cooling effect in

$$\eta_c = \frac{\lambda_{pump} - 1}{\lambda_{emit}}$$

## Anti Stokes Physics

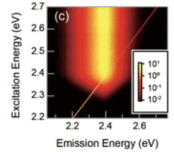
**Quantum Efficiency**  
 The Quantum Efficiency (QE) is related to how the laser power is transformed

$$QE = \frac{W_{rad}}{W_{rad} + W_{nr}} \approx 1$$

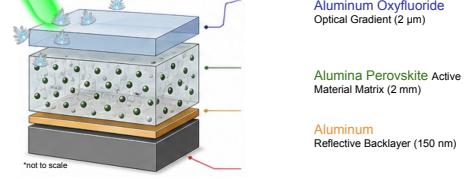
Non radiative decay will convert power into heat which takes away from cooling potential

### Cooling Condition

Measured Emission vs excitation intensity plot from primary source. Below the line indicates cooling regime. The plot demonstrates the small range of laser light energies that can be used to achieve cooling.



### Macroscopic Structure



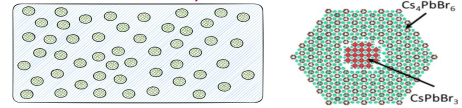
- Aluminum oxynitride used to reduce Fresnel losses and increase efficiency via a gradient in refractive index
- Alumina Perovskite matrix is the active material that upconverts the laser light to produce cooling
- Back reflector enhances upward emission and reflects any unabsorbed photons back

## Final Design

### Performance Targets

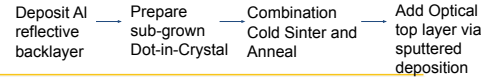
Device Heat Load	800W/cm <sup>2</sup>
Required active material thickness	2mm
Response Time	<1s
Laser Wavelength	532 nm
Laser power required	~100W
Cooling Efficiency η <sub>c</sub>	2.66%
Quantum Efficiency	0.98

### Microscopic Structure



Alumina provides high thermal conductivity and transparency while closely matching the refractive index of the perovskite crystals.

### Manufacturing Process



## Thermal Simulations & Analysis

PL quantum efficiency and the cooling gain under maximum excitation.

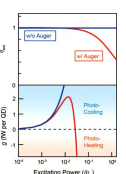
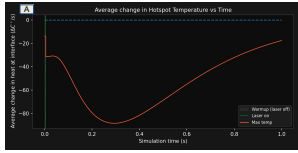
β represents the probability of a single QD being excited per unit time, which is assumed to be proportional to the excitation intensity. Idealized max cooling is

Beyond this optimal excitation density, the system transitions from single exciton recombination removing heat to multiexciton recombination that adds heat defining a strict

Fick's second law

$$I = I_0 e^{-\mu d}$$

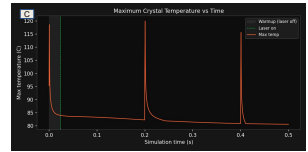
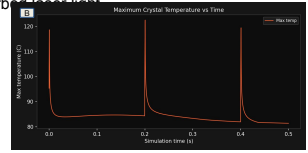
$$\rho C_p \frac{\partial T}{\partial t} - \nabla \cdot (k \nabla T) = q_v$$



Plot A indicates the rate of temperature change the optical cooler delivers to the chip surface over time. The plot indicates that a saturation of temperature change occurred at about 0.3 seconds before the cooled spot dropped below ambient temperature and heat flowed in from the surrounding.

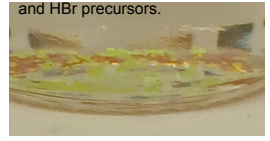
Plots B and C are for 1 millisecond 800W/cm<sup>2</sup> hotspot pulses. B is with no laser cooling C is hotspot pulses lined up with cold side saturation time in plot A. A reduction in max temperature by 2-3°C per hotspot peak which corresponds to a direct chip performance increase.

Design parameters for simulation plots:  
 2mm active layer  
 532nm pump wavelength  
 1% volume fraction of QD  
 1200W/cm<sup>2</sup>



## Prototype & Test Results

Current Progress:  
 Synthesised the quantum dots within the perovskite matrix from CsBr, PbBr<sub>2</sub>, and HBr precursors.



### Planned Characterization

- TEM (Transmission Electron Microscopy)**  
 Examine QD size distribution and dispersion
- Raman Spectroscopy**  
 Estimate the quantum efficiency
- Photoluminescence spectrum**  
 Confirm emission wavelength and anti-stokes behavior

